

11-02-05

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TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT

(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.**15436.51.1**

In Re Application Of:

Aronson, et al.

Application No.

10/687,107

Filing Date

10/16/2003

Examiner

unknown

Customer No

022913

Group Art Unit

2816

Confirmation No.

7228

Title:

FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS CONNECTIONS TO OPTICAL SUBASSEMBLIES

Address to:

Commissioner for Patents**P.O. Box 1450****Alexandria, VA 22313-1450****37 CFR 1.97(b)**

1. ☒ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

37 CFR 1.97(c)

2. ☐ The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

☐ the statement specified in 37 CFR 1.97(e);

OR

☐ the fee set forth in 37 CFR 1.17(p).

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 197(b) or 1.97(c))

Docket No.
15436.51.1

In Re Application Of:

Aronson, et al.

Application No. 10/687,107	Filing Date 10/16/2003	Examiner unknown	Customer No 022913	Group Art Unit 2816	Confirmation No. 7228
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Title:
FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS CONNECTIONS TO OPTICAL SUBASSEMBLIES

Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- ☐ A check in the amount of \$ _____ is attached.
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October 31, 2005

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Kari W. Jensen
Signature

Dated: 10/31/05

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Applicant(s): Aronson, et al.

Docket No.
15436.51.1Application No.
10/687,107Filing Date
10/16/2003Examiner
unknownCustomer No
022913Group Art Unit
2816

Invention.

FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS CONNECTIONS TO OPTICAL SUBASSEMBLIES

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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Aronson, et al.

Art Unit

2816

FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS CONNECTIONS TO OPTICAL SUBASSEMBLIES

UNDER 37 C.F.R. § 1.97

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please find, pursuant to 37 C.F.R. § 1.98(a)(1), the enclosed Form PTO-1449 which contains a list of all patents, publications, or other items that have come to the attention of one or more of the individuals designated in 37 C.F.R. § 1.56(c). While no representation is made that any of these references may be "prior art" within the meaning of that term under 35 U.S.C. §§ 102 or 103, the enclosed list of references is disclosed so as to fully comply with the duty of disclosure set forth in 37 C.F.R. § 1.56.

Moreover, while no representation is made that a specific search of office files or patent office records has been conducted or that no better art exists, the undersigned attorney of record

believes that the enclosed art is the closest to the claimed invention (taken in its entirety) of which the undersigned is presently aware, and no art which is closer to the claimed invention (taken in its entirety) has been knowingly withheld.

The accompanying Form PTO-1449 notifies the Examiner of the specified related pending U.S. patent applications listed therein. This notice is not an admission that the claims of the present application and the claims of the specified related pending patent applications are substantially similar or that the specified related applications represent prior art with respect to the present application.

In accordance with 37 C.F.R. §§ 1.97 and 1.98, a copy of the listed non-U.S. patent references or relevant portion thereof is also enclosed.

This Information Disclosure Statement is being filed before a first Office Action on the merits has been received, therefore, no fee is believed to be due. Please credit any over payment or charge any additional fees to Deposit Account No. 23-3178 of the undersigned.

DATED October 31, 2005.

Respectfully submitted,



Kevin W. Stinger
Attorney for Applicant
Registration No. 48,959
Customer No. 022913

KWS: gj
gh0000000541V001

Applicant: Argenson, et al.

Serial No.: 10/487,107

Att'y Docket No.: 15436.51.1

Filing Date: October 16, 2003

Group: 2816

For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIESINFORMATION DISCLOSURE CITATIONS MADE BY APPLICANTRelated U.S. Patent Applications

	<u>Inventor</u>	<u>Application Number</u>	<u>Filing Date</u>
_____ 1	Kumar, et al.	10/409,837	04/09/2003
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_____ 5	Ice, Donald A.	11/179,223	07/11/2005
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<u>Examiner Initial*</u>	<u>Document Number</u>	<u>Issue/Pub Date</u>	<u>Name</u>
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_____ 13	4,818,099	04/04/1989	Preikschat, et al.

Examiner:

Date Considered:

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609, draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Applicant: Aronson, et al.

Serial No.: 10/687,107

Att'y Docket No.: 15436.51.1

Filing Date: October 16, 2003

Group: 2816

For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIES

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Applicant: Aronson, et al.

Serial No.: 10/687,107

Att'y Docket No.: 15436.51.1

Filing Date: October 16, 2003

Group: 2816

For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIES

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For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIES

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Date Considered:

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 Serial No.: 10/687,107
 Filing Date: October 16, 2003
 For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
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Att'y Docket No.: 15436.51.1
 Group: 2816

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<u>Examiner Initial*</u>	<u>Document Number</u>	<u>Publication Date</u>	<u>Country or Patent Office</u>
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(including author, title, pertinent pages, etc.)

Examiner
Initial*

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Applicant: Aronson, et al.
Serial No.: 10/687,107 Att'y Docket No.: 15436.51.1
Filing Date: October 16, 2003 Group: 2816
For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIES

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- ____ 83 COLDREN, et al., "Flip-Chip Bonded, Back-Emitting, Microlensed Arrays of Monolithic Vertical Cavity Lasers and Resonant Photodetectors," Electronic Components and Technology Conference, Sept. 1999, pp. 733-740
- ____ 84 HAVANT, "Flexible Interposing Carrier Scheme for Optical Waveguides," Research Disclosure No. 303, July 1989, page 512
- ____ 85 HIBBS-BRENNER, et al., "Packaging of VCSEL Arrays for Cost-Effective Interconnects at <10 Meters," Electronic Components and Technology Conference, Sept. 1999, pp. 747-752
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- ____ 88 LOUDERBACK, et al., "Flip Chip Bonded Arrays of Monolithically Integrated, Microlensed Vertical-Cavity Lasers and Resonant Photodetectors," IEEE Photonics Technology Letters, March 1999, pp. 304-306, Vol. II, No. 3.
- ____ 89 PLAWSKY, et al., "Photochemically Machined, Glass Ceramic, Optical Fiber Interconnection Components," Article, Optoelectronic Materials, Devices, Packaging and Interconnects (1998), SPIE, Vol. 994, pp. 101-106
- ____ 90 SULLIVAN, et al., "Polymeric Waveguides," 1992 IEEE, pp. 27-31

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References Cited by Applicants

While the filing of Information Disclosure Statements is voluntary, the procedure is governed by the guidelines of Section 609 of the Manual of Patent Examining Procedure and 37 C.F.R. §§ 1.97 and 1.98. To be considered a proper Information Disclosure Statement, Form PTO-1449 shall be accompanied by a copy of each listed patent or publication or other item of information and a translation of the pertinent portions of foreign documents (if an existing translation is readily available to the applicant), an explanation of relevance of each reference not in the English language, and should be submitted in a timely manner as set out in MPEP Sec. 609.

Examiners will consider all citations submitted in conformance with 37 C.F.R. § 1.98 and MPEP Sec. 609 and place their initials adjacent the citations in the spaces provided on this form. Examiners will also initial citations not in conformance with the guidelines which may have been considered. A reference may be considered by the Examiner for any reason whether or not the citation is in full conformance with the guidelines. A line will be drawn through a citation if it is not in conformance with the guidelines AND has not been considered. A copy of the submitted form, as reviewed by the Examiner, will be returned to the applicant with the next communication. The original of the form will be entered into the application file.

Each citation initialed by the Examiner will be printed on the issued patent in the same manner as references cited by the Examiner on Form PTO-892.

The reference designations "A1," "A2," etc. (referring to Applicant's reference 1, Applicant's reference 2, etc.) will be used by the Examiner in the same manner as Examiner's reference designations "A," "B," "C," etc. on Office Action Form PTO-1142.

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Examiner:

Date Considered:

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609, draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.
